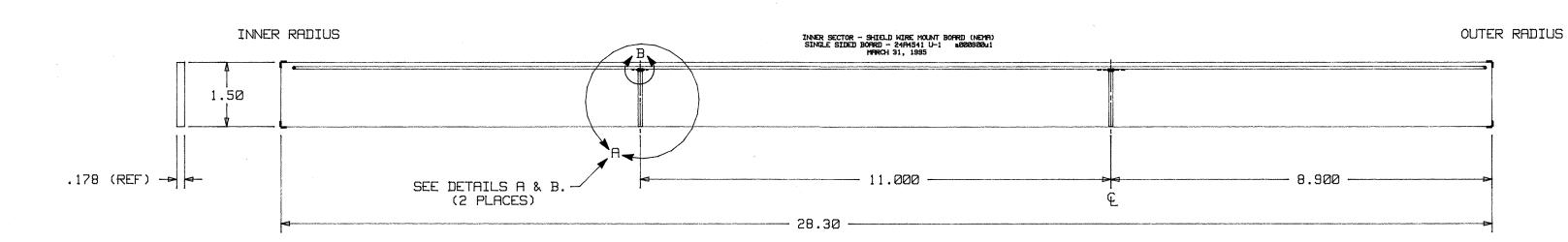
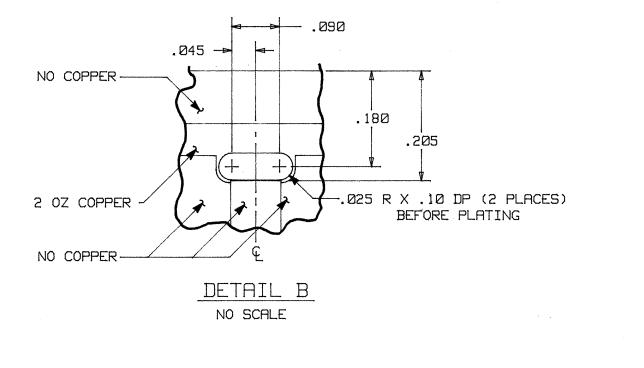
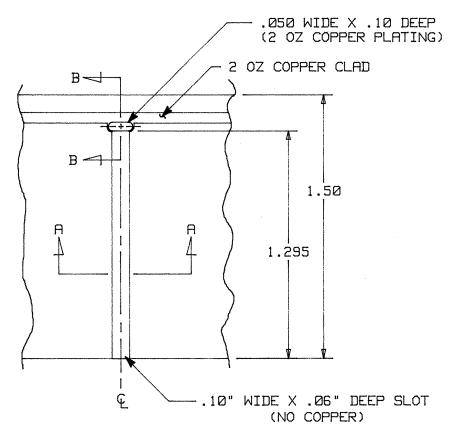
REV. DATE CHKD. DATE CHANGES DRAWN

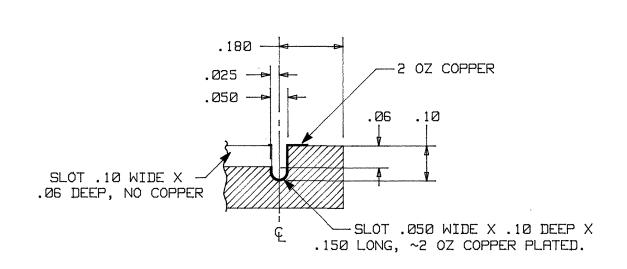


WIRE MOUNT SIDE VIEW SCALE: ~.5:1

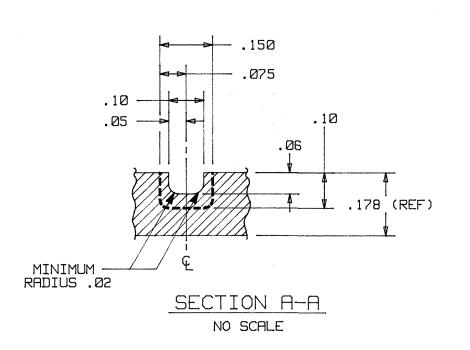




DETAIL A NO SCALE



## SECTION B-B NO SCALE



## NOTES:

- 1. BOARD MATERIAL: .178 THICK NEMA G10, CERTIFIED BROMIDE FREE, 2 OZ. COPPER CLAD - ONE SIDE. THERE IS NO TIN PLATING ON THIS BOARD. MATERIAL WILL BE SUPPLIED BY LBL. THIS IS A SINGLE SIDEO BOARD.
- 2. MANUFACTURER MAY NOT PUT ANY IDENTIFICATION NOMEN-CLATURE ON PRINTED CIRCUIT BOARD, EITHER SIDE.
- 3. BOARD SIZE IS 28.30 LONG X 1.50 WIDE X .178 THICK. DIMENSIONS ARE IN INCHES. TOLERANCES ARE .XX = .015 AND .XXX = .005.
- 4. CREATE SLOTS BEFORE COPPER PLATING.
- 5. FINAL BOARD DIMENSIONS ARE 28.100 LONG X 1.389 WIDE X .178 THICK. SEE DRAWING 24A4594 FOR MILLING ROUTING INSTRUCTIONS. FINAL ROUTING TO SE CONE BY LEL
- 6. REFERENCE DRAWINGS:

24A4534 M-2 a000900m2 BOARD OULINE/FABRICATION -PANEL OF 10 BOARDS -ELECTRONIC DEPARTMENT

2484594

SHIELD WIRE MOUNT BOARD (RIGHT SIDE, G-10) FAB. FROM MECHANICAL DEPARTMENT)X

D	ı;		TITE STAR TPC						
I	I II:		INNER SECTOR ELECTRONICS						
T	T III:		SHIELD GRID WIRE MOUNT BOARD (RIGHT,G10)						
SHOWN			BOARD OUTLINE/FABRICATION						
ACCOUNT 8052-24			DRAWN STIRKKINEN	DETTE 23/31/95	LAWRENCE BERKELEY LABORATORY				
SERIAL NUMBER			CHECKED	DATE	UNIVERSITY OF CALIFORNIA				
DATE NO.		APPRÔVED	DATE	OFFICE OF ELECTRONICS ENGINEERING					
ISSUED REQD.		ENGINEER	<u> </u>	FILE NO.	SIZE	DRAWING NO.		REV.	
DATE REQD.		ENGINEER FREI	BIESER	a000900m1	3	248454	3 M-1		
DEL.			SCALE NONE	E2,E5,E12			SHEET 1 OF	. 2	